

Sheet 1 of 1 Docket No.: Bao 16-25-12

Serial No.09/603,941 Applicants: Bao et al..

Filing Date: 06/27/2000 Group: TBA

EXAMINER INITIALS *		DOCUMENT NUMBER	DATE	NAME		CLASS	SUB- CLASS	FILING DATE
Bec	A	5,693,566	12/02/1997	Cheung				
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Mr.	E	J.L. Hedrick et al., "Toughened, Inorganic-Organic Hybrid Materials For Microelectric Application", Mat. Res. Soc. Symp. Proc., Vol. 443, Material Research Society, 1997, pp. 47-58.						
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draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant.

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12/31/01